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FOR IMMEDIATE RELEASE

Press Release

YINCAE Launches Breakthrough Thermal Underfill: UF 158A2

(Albany, NY) 03/26/2023 — YINCAE, a leading manufacturer of high-performance electronic materials, has announced the release of its breakthrough product: Thermal Underfill - UF 158A2.

Designed for use in a variety of electronic devices, not only can UF 158A2 replace underfill, silver epoxy paste and thermal pad/paste in one step in CoWoS package, but also provides superior protection and improved thermal management for critical components. By filling the space between the device and The PCB (Printed Circuit Board), Thermal Underfill enhances the structural integrity of the assembly while reducing stress on solder joints. UF 158A2 is ideal for use in high-reliability applications where temperature cycling, shock, and vibration can cause damage to electronic components. The product features excellent thermal conductivity and high-temperature stability, ensuring optimal performance even in the most demanding environments.

"We are excited to introduce UF 158A2 to our product portfolio," said Dr. Wusheng Yin, CEO of YINCAE. "Our team of engineers and scientists have worked tirelessly to develop a product that meets the growing demands of the electronics industry. We believe that UF 158A2 will provide our customers with a reliable and cost-effective solution: Fast flow and easy to underfill 100x100 mm chip, Shortened Manufacturing Process, High thermal conductivity 3-4W/mk, Snap cure and it is Reworkable. UF 158A2 also has a huge cost saving, for their thermal management needs."

UF 158A2 is available in a variety of formulations to suit different application requirements. The product is easy to apply and can be cured at low temperatures, making it suitable for use with a range of electronic devices. With its exceptional performance, reliability, and ease of use, UF 158A2 is set to become a key player in the electronics industry.

For more information on YINCAE's UF 158A2, or to learn more about what YINCAE offers, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of thermal interface materials, underfill solutions, die attach adhesives, electronic materials, & high-performance coatings used in microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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